

IN THE CLAIMS:

The following listing of claims will replace all prior listings of claims in the application:

1. (Currently Amended): A system for cooling a processor, the system comprising a hybrid heat transport module configured to be thermally coupled to the processor and to a fansink that includes at least one air channel, the hybrid heat transport module comprising:

a plurality of [[an]] air channels adapted for removing heat from the processor and configured to interface to the at least one air channel of the fansink; and

a fluid channel including an inlet and an outlet adapted for further removing heat from the processor; and

a bottom plate that is coupled to the plurality of air channels and the fluid channel and configured to be thermally coupled to the processor.

2. (Currently Amended): The system of claim 1, further comprising a pump that is coupled to the inlet and the output of ~~wherein~~ the fluid channel forming [[is]] a closed loop channel.

3. (Currently Amended): The system of claim ~~[[1]]~~2, wherein the ~~hybrid module is coupled to a pump~~ is adapted for circulating the heat transfer fluid through the fluid channel.

4. (Currently Amended): The system of claim 3, further comprising a heat exchanger that is coupled between the outlet and the pump and configured to dissipate heat from

wherein the heat transfer fluid in the fluid channel ~~transports heat from the processor to~~
~~a heat exchanger~~ into an outside environment.

5. (Currently Amended): The system of claim 1, wherein ~~[[a]]the~~ bottom plate of
includes a trench that is sized for coupling to and sealing the fluid channel ~~is textured.~~

6. (Currently Amended): The system of claim ~~[[5]]1~~, wherein the ~~texture of the~~ bottom
plate comprises a plurality of pins extending upward from the bottom plate into the fluid
channel.

7. (Currently Amended): The system of claim 1, wherein the hybrid heat transport
module is adapted for dissipating heat from the processor through air, through a fluid, or
through both air and fluid.

8. (Currently Amended): The system of claim 1, further comprising a thermal
adhesive disposed on ~~[[a]]the~~ bottom plate of ~~the hybrid module~~ for thermally coupling
the hybrid heat transport module to the processor.

9. (Currently Amended): The system of claim 1, wherein the fansink comprises:
a fan configured to force air through the at least one air channel of the fansink and
the plurality of air channels; and
the at least one [[an]] air channel that is adapted for removing heat from the
processor,
wherein the fansink is ~~configured to be thermally-coupled to the~~ bottom plate
processor.

10. (Cancelled)

11. (Currently Amended): The system of claim 9, wherein the fansink and the hybrid heat transport module are adapted for simultaneous operation.

12. (Currently Amended): The system of claim 9, wherein the fansink and the hybrid heat transport module are adapted for independent operation.

13. - 15. (Cancelled)

16. (Original): The system of claim 1, wherein the system is sized to cool a memory chip in addition to the processor.

17. (Currently Amended): A method for cooling a processor, the method comprising the steps of:

continually cooling the processor by forcing using forced air through at least one air channel of a core cooling module that is thermally coupled to the processor to

remove heat from the processor;

monitoring a temperature of the processor; and

circulating a heat transfer fluid in a fluid channel of a hybrid heat transport module that is thermally coupled to the processor module to further remove heat from

the processor when the processor reaches a threshold temperature.

18. (Currently Amended): The method of claim 17, further comprising the step of ceasing to circulate the heat transfer fluid through the fluid channel when the processor is cooled to a desired temperature.

19. (Currently Amended): The method of claim 17, wherein the heat transfer fluid is circulated by turning on a pump that is coupled to the fluid channel to form a closed loop channel.

20. (Currently Amended): The method of claim [[18]] 19, further comprising the step of transporting the heat transfer fluid through a heat exchanger that is coupled between an outlet of the fluid channel and the pump and adapted to dissipate heat from the heat transfer fluid into an outside environment.

21. (New): The system of claim 5, wherein the trench is textured to increase a heat transfer surface area of the bottom plate.

22. (New): The method of claim 17, further comprising the step of forcing air through a plurality of air channels that are included in the hybrid heat transport module.

23. (New): The method of claim 17, wherein at least a portion of the fluid channel is textured to increase a heat transfer surface area of the fluid channel.

24. (New): The method of claim 17, wherein a plurality of pins extend into the fluid channel to transfer heat from the processor to the fluid in the fluid channel.